

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

SSOP

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**TOTAL MASS (g) : 0.235911**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.008916	1000000	37793.9138064779		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.122431	975000	518971.137420468		
		Iron (Fe)	7439-89-6	0.003014	24000	12776.0045101754		
		Phosphorus (P)	7723-14-0	0.000038	300	161.077694554302		
		Zinc (Zn)	7440-66-6	0.000088	700	373.022029494174		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.125571</b>	<b>1000000</b>	<b>532281.241654692</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.003749	1000000	15891.5862337916		
		<b>External Plating Total:</b>				<b>0.003749</b>	<b>1000000</b>	<b>15891.5862337916</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001005	1000000	4260.08113229141		
<b>Internal Plating Total:</b>				<b>0.001005</b>	<b>1000000</b>	<b>4260.08113229141</b>		
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000022	50000	93.2555073735434		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000132	300000	559.53304424126		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000286	650000	1212.32159585606		
<b>Die Attach Total:</b>				<b>0.000440</b>	<b>1000000</b>	<b>1865.11014747087</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.009848	103000	41744.5562097571		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.085571	895000	362725.773702795		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000191	2000	809.627359470309		
		<b>Encapsulation Total:</b>				<b>0.095610</b>	<b>1000000</b>	<b>405279.957272022</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000620	1000000	2628.1097532544		
					<b>TOTAL MASS (g) :</b>	<b>0.235911</b>		